



## ***S-Cubed* PROVIDES VALUE ENGINEERED WAFER PROCESSING SYSTEMS TO THE SEMICONDUCTOR AND ALLIED INDUSTRIES...**

***COAT***

***DEVELOP***

***BAKE***

***SCRUB***

The ***S-Cubed*** ( $S^3$ ) product offering includes:

- **Flexi-PCS™** spin processing systems for photoresist and similar applications in **compound semiconductors, MEMS, packaging and more**
  - Controlled environment ( $N_2$  purged, oxygen free, etc.) **hot plates** and systems for up to 450°C for both photolithographic and other processes requiring programmable and precise substrate heating
  - **Optical edge-bead** exposure modules and systems for removal or curing
- **TruClean™** systems using double-sided scrubbing (patented) and megasonic technology
- **Cyclone™** small footprint, chemical processing systems (acids, solvents, high pressure spray)
- Special purpose tools designed and built to solve customer problems from our library of skills including, bonding, fiber handling, alignment, servo control, image analysis, temperature control, power control, position control, and robotics.

New control technology has enabled a substantial reduction in cost, permitting  $S^3$  to offer new equipment at costs that often are lower than used or rebuilt equipment, while offering superior process capability, reliability and new equipment warranty.

## **Flexi-PCS™**

## **Value Engineered Wafer Processing Systems**



### **Spin Coat, Develop, Bake**

- PC Based with Color LCD Touchscreen Interface
- Unlimited Process Storage Capabilities
- Remote Data Collection and Control
- Non-Contact Optical Centering
- Stacked Thermal Modules
- Process Substrates, 2" to 200 MM
- Proven Modular Design
- Minimal Parts Count for Ultra High Reliability
- Small Footprint

### **Edge Exposure for Removal or Curing**

- Non-contact Optical Wafer Centering for Clean Wafer Placement
- 0.5 to 7 mm Exposure Width
- 365-380 nm Bandwidth Standard
- Programmable Exposure Energy with Closed Loop Control
- Small Footprint
- Process Substrates 2" to 200 MM
- Servo Controlled Positioning
- Track Flats or Notches
- Dual Cassette or System Interface

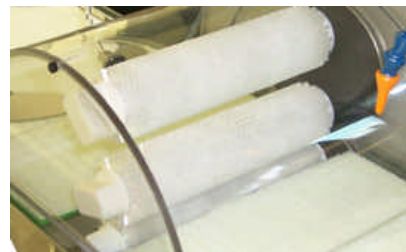




## **TruClean™ Double-Sided Scrubbing Systems**

Round Square Rectangular Thick Thin ...to 300MM

Two Brush Sets of PVA, Nylon or Combination  
Programmable Brush Speed and Pressure  
Cassette to Cassette or Manual Load/Unload Systems  
Patented Scrub Module with NO Belts  
DI Water, Ozonated or RCA Clean Input Baths  
Stainless and Polypro Cabinetry with ULPA Filtration  
PC Based System with LCD Touchscreen Operation  
Spin Rinse Dry with Megasonic Post Scrub Rinse Available  
Compact Design with Bulkhead Mounting Options



## **Cyclone™ Chemical Processing Systems**

Cleaning Etching Liftoff  
Cassette to Cassette or Manual Load/Unload Systems  
High Pressure Spray  
Spin Rinse Dry  
TFE and Stainless Steel Chamber Options  
PC Based System with LCD Touchscreen Operation  
Aluminum Construction with Polypro Cabinetry



Manual load, high pressure solvent spray system shown



## **Flexi-HP™ Stand Alone Hot Plates or Bake Systems**

Bake Temps to 450° C Up to 300 MM

Programmable Proximity, Fixed Proximity or Vacuum Pulldown  
N<sub>2</sub> Purge Option for Low Oxygen Baking  
Exhausted 19" x 19" Freestanding Module  
Optional Automatic Cassette-to-Cassette Load/Unload  
Temperature Uniformity +/-0.5°C to 150°C, +/-0.5%



## **Flexi-TPE™ Ultra-Uniform Hot Plates**

Bake Temps to 425° C Up to 300 MM  
Proximity or Vacuum Pull-down N<sub>2</sub> Purge Option  
19" x 19" Freestanding Module

*New Hot Plate Technology Provides Temperature  
Uniformity to 0.1° C across plate to 300 MM*



Value Engineered Process Systems

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